



# **Metrology for MOCVD of VCSELs – latest progress for enabling high-yield manufacturing**

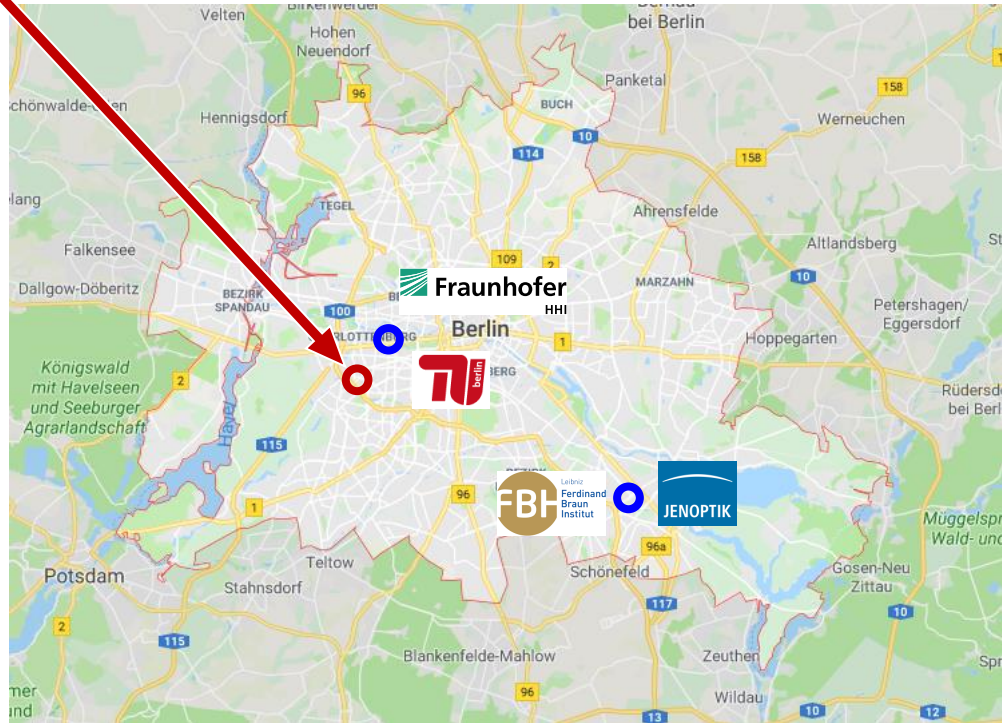
Dr. Christian Kaspari

LayTec AG





**founded 1999 in Berlin**  
**spin-off of TU Berlin**  
**20 years old**  
**65 employees**  
**2500 systems sold**  
**operating worldwide**



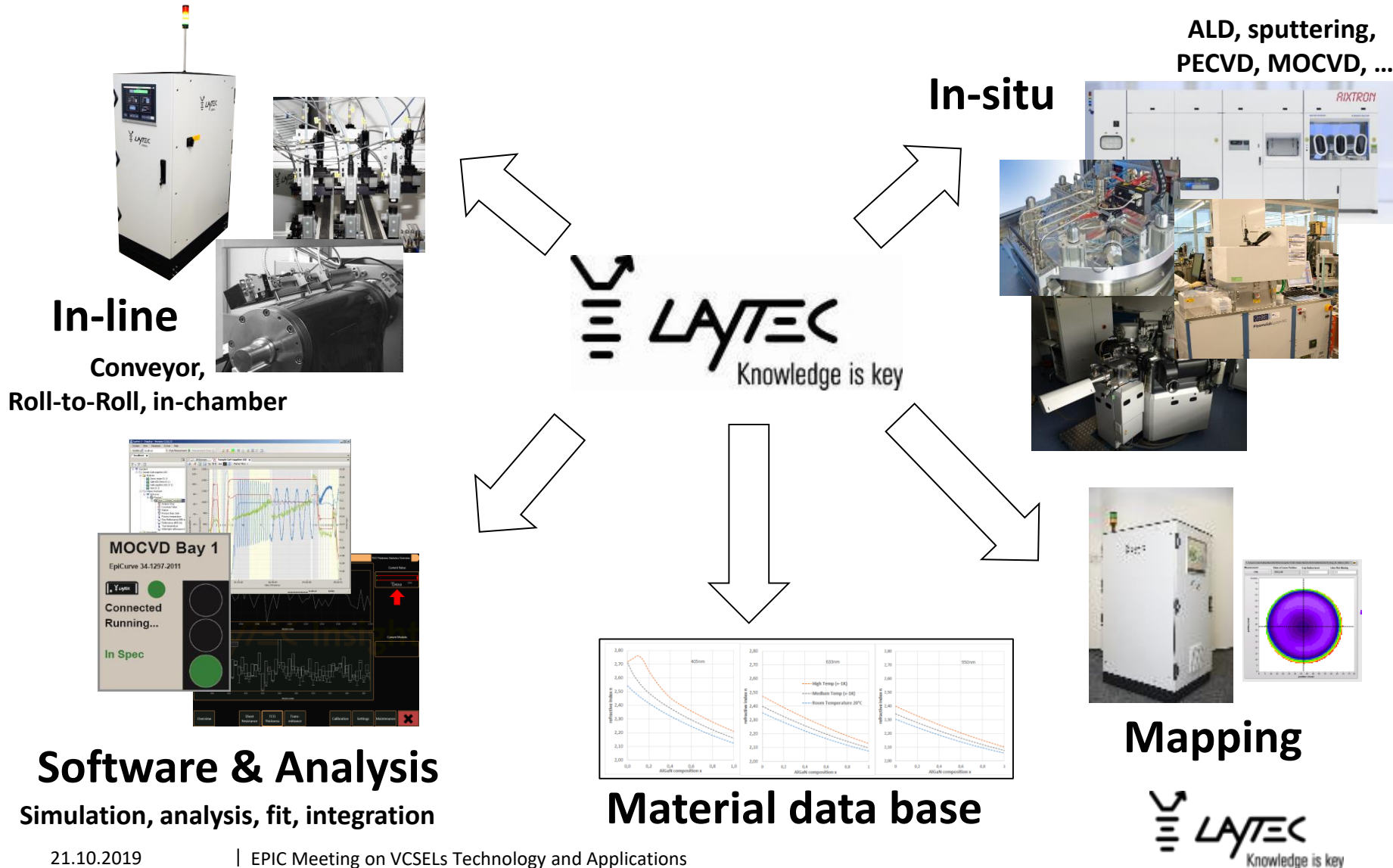
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**Our business: Process-integrated optical metrology**

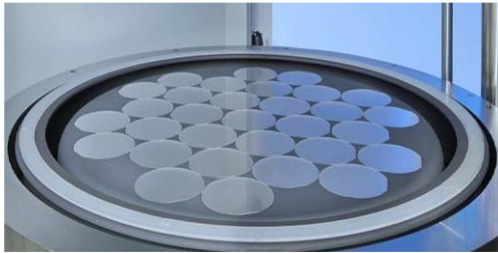
**Our markets: Semiconductor and thin-film industry & academia  
incl. lighting, laser, photovoltaics, glass coating ...**



# Integrated metrology for various industries and markets

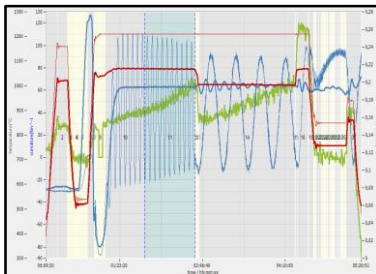
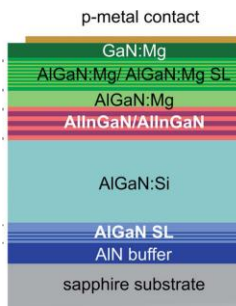


# in-situ metrology in semiconductor industry



substrate wafers

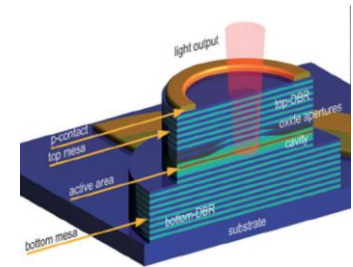
**process control**  
= monitoring and control of  
deposition or growth  
process



optical in-situ metrology tool



deposition system (e.g. MOCVD)



semiconductor device  
(e.g. VCSEL)

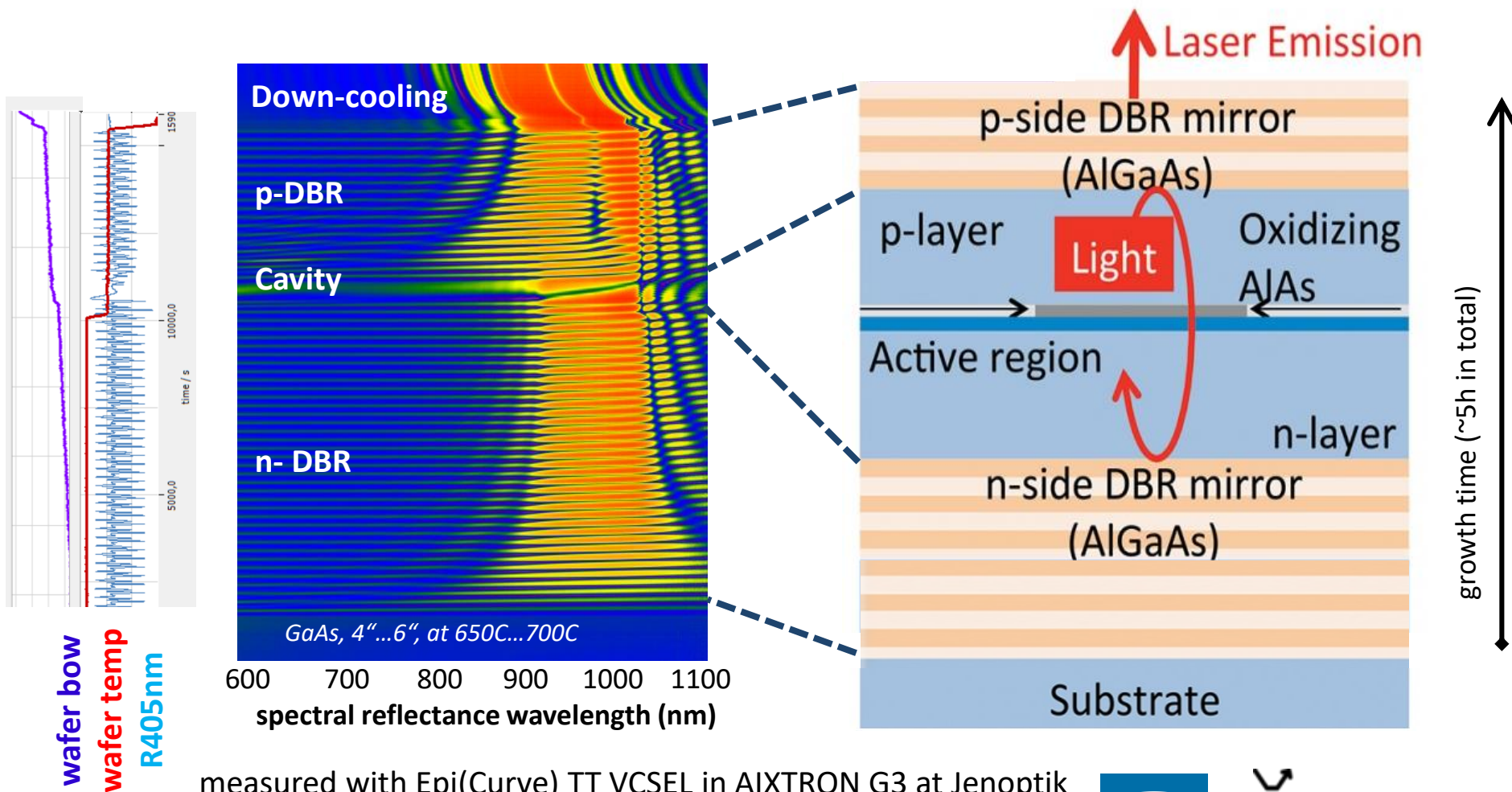
- Measurement of**
- temperature
  - layer thickness / growth rate
  - ternary composition
  - curvature / bow
  - surface morphology
  - **spectral reflectance**





# Example of in-situ metrology of a VCSEL structure

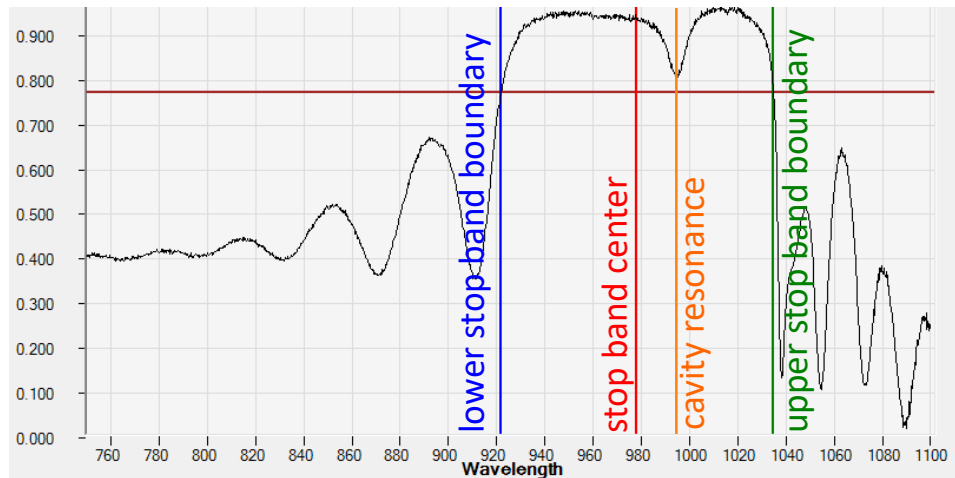
Goal: reliable prognosis of device properties by in-situ spectral reflectance



measured with Epi(Curve) TT VCSEL in AIXTRON G3 at Jenoptik

# Example of in-situ metrology of a VCSEL structure

- Real-time analysis (during run) allows determination of parameters like stop band boundaries, stop band center and cavity resonance dip wavelength (+many more parameters)



Single reflectance spectrum during growth of p-DBR:

- thermal shift (+broadening)
- cavity resonance dip not in the center of the stop band
- In this case: recipe tuning needed
- But: a certain asymmetry is expected at  $T_{\text{growth}}$  because thermal shift (GaAs) > thermal shift (AlAs)

- Spectroscopic reflectance with time resolution of 100Hz enables determination of lateral homogeneity (center-edge comparison)

# Current metrology challenges for VCSEL/DBR/SESAM

„Standard“ requirements

e.g. for **edge emitting lasers**

Growth rate =  $0.500 \pm 0.005$  nm/s  $\Rightarrow \sim \pm 1\%$

Today's advanced requirements

e.g. for **VCSEL** emission wavelength ( $940 \pm 1$ )nm

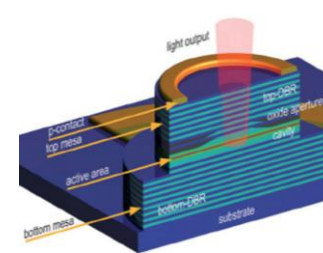
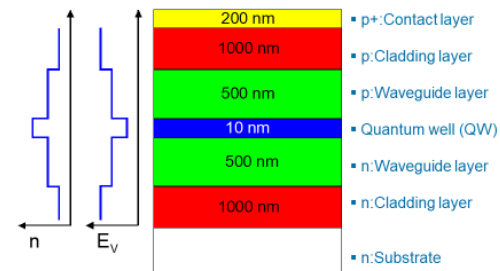
Growth rate =  $0.5000 \pm 0.0005$  nm/s  $\Rightarrow \sim \pm 0.1\%$

**High-yield manufacturing is not possible without in-situ metrology!**

**Epitaxy makes up ~80% of VCSEL production costs.**

**Tasks for in-situ metrology:**

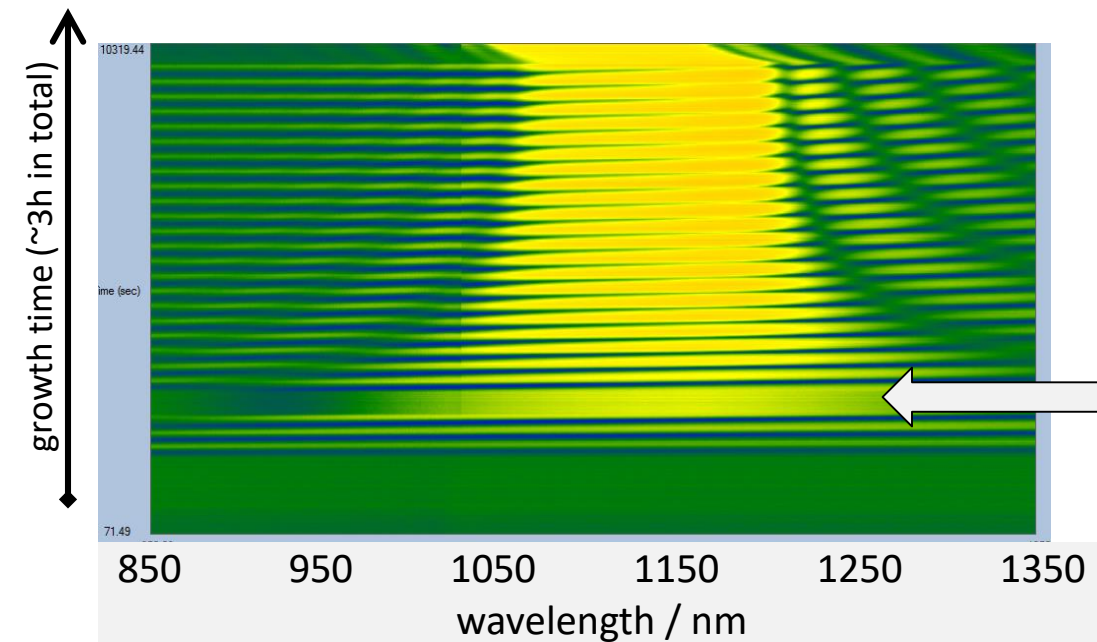
- spectral in-run analysis
- accuracy in growth rate measurement
- integration into MOCVD for advanced process control (such as feed-forward control)



- >100 layers; >5μm stack
- thin layers (DBR, MQW)
- graded interfaces in DBRs
- pyrometry may be blocked by DBR

## Example: SESAM ( $1030 \pm 1$ )nm – feed-forward control

- SESAM: semiconductor saturable absorber mirror
- 25 pairs of GaAs/AlAs
- Full load in AIXTRON G3 reactor
- DBR Stop-Band: 990-1090nm (RT); 1030-1200nm (high T, up-shifted)

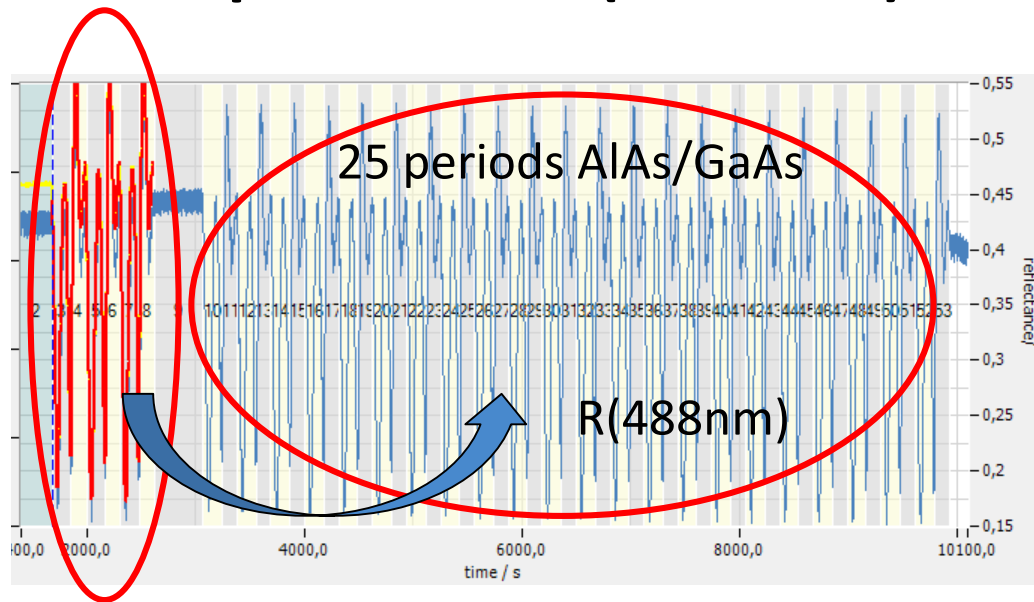


Spectral reflectance finger-print  
(850-1350nm, ~3h of epi, cool-  
down wavelength shift is seen)

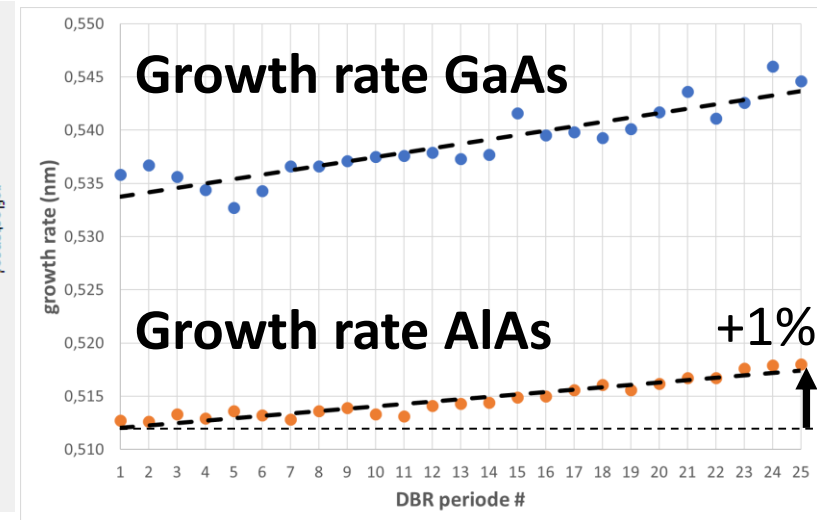
**Epi pause** - for 6-layer (3 DBR periods)  
growth rate analysis and recipe feed-  
forward update



## Example: SESAM (1030 $\pm$ 1)nm – feed-forward control

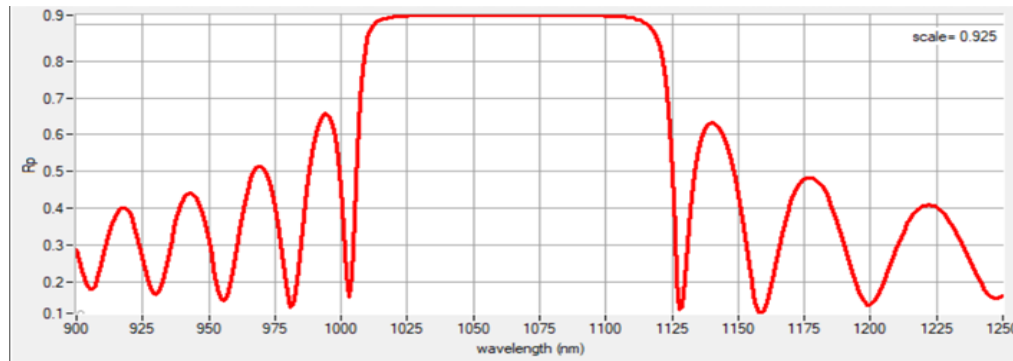


- Determine growth rates of GaAs and AlAs during first 3 DBR periods
- Transmit growth rate to growth system
- Update growth times in recipe („feed forward“)
- grow remaining 22 periods



- Detailed analysis of in-situ data show linear increase of growth rates over 25 periods
- Tiny effect, but important
- Must be taken into account to achieve desired accuracy

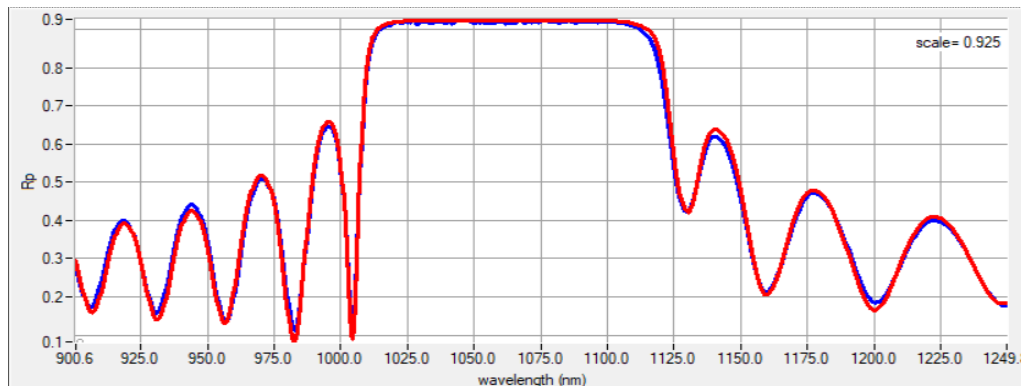
## Example: SESAM - ex-situ growth rate analysis



Calculated reflectance spectrum of ideal DBR would be highly symmetric

Growth rate  $_{\text{GaAs}} = 0.497 \text{ nm/s}$

Growth rate  $_{\text{AlAs}} = 0.580 \text{ nm/s}$



**Blue:** Measured DBR spectrum; asymmetric

**Red:** Analytic model based on in-situ measured growth rates with linear increase

Growth rate  $_{\text{GaAs}} = 0.4955 \text{ nm/s} \rightarrow 0.4990 \text{ nm/s}$  (+1% from start of DBR to end of DBR)

Growth rate  $_{\text{AlAs}} = 0.5769 \text{ nm/s} \rightarrow 0.5839 \text{ nm/s}$  (+1% ...)

## Excellent agreement to measured ex-situ reflectance spectrum

# Acknowledgements & Cooperations



Martin Zorn  
JENOPTIK Diode Lab GmbH, Berlin, Germany

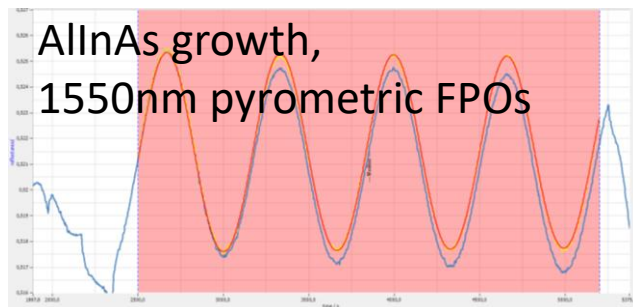


Leibniz  
Ferdinand  
Braun  
Institut

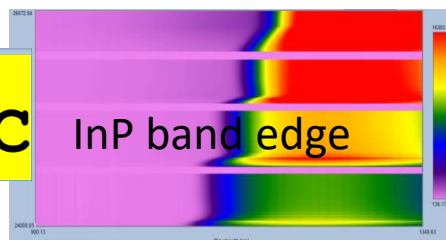
Andre Maaßdorf, Markus Weyers  
Ferdinand-Braun-Institut, Berlin, Germany



AlInAs growth,  
1550nm pyrometric FPOs



InP WSI  
318.0°C

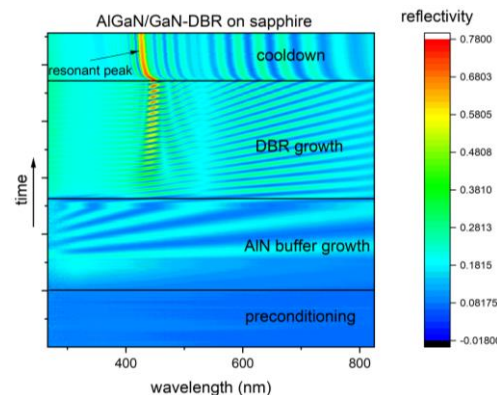


**Helping the WSI Munich to transfer growth processes for long wavelength VCSELS from research MBE to production MBE:**

- precise growth rate determination using pyrometric FPOs
- GaAs/InP band edge temperature system to transfer exact process temperatures



**Metrology for GaN-based VCSELS (EpiTT VCSEL UV)**



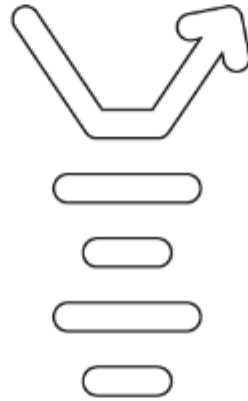
## Summary...

- We have developed new spectroscopic analyses for resonant structures and new procedures for measuring the growth rates of thin layers (with composition grading) in highly complex device structures.
- High-yield manufacturing of current cutting-edge devices like VCSEL/ DBR/ SESAM can only be facilitated by close integration of in-situ metrology into the MOCVD tools (e.g. feed-forward control schemes).
- Ex-situ mapping of Epi uniformity achieves a new level of accuracy by feeding in the results of in-situ analysis.

## ... and beyond

- We are looking for close collaborations with VCSEL foundries and their customers, e.g.:
  - develop and test new comprehensive control concepts
  - use in-situ results for advanced mapping schemes

# Knowledge is key



[www.laytec.de](http://www.laytec.de)



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